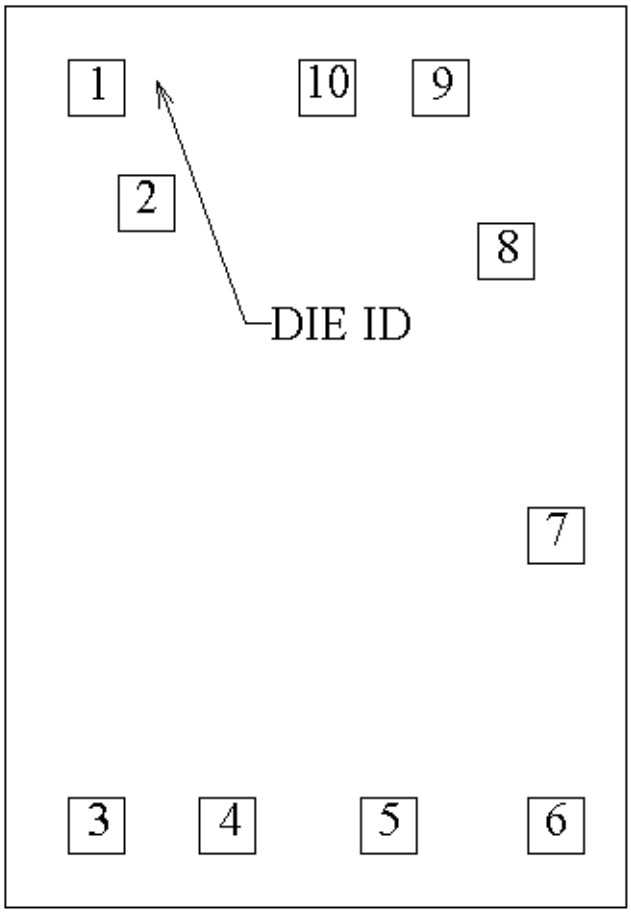
LM361 MDC MWC
HIGH SPEED DIFFERENTIAL COMPARATORS

March 19,2002

DIE LAYOUT (E-STEP)



DIE/WAFER CHARACTERISTICS

Fabrication Attributes		**General Die Information**	
Physical Die Identification	LM161E	Bond Pad Opening Size (min)	86µm x 86µm
Die Step	E	Bond Pad Metalization	ALUMINUM
Physical Attributes		Passivation	VOM NITRIDE
Wafer Diameter	150mm	Back Side Metal	Bare Back
Die Size (Drawn)	965µm x 1397µm 38mils x 55mils	Back Side Connection	Floating
Thickness	330µm Nominal		
Min Pitch	177µm Nominal		

Special Assembly Requirements:
Note: Actual die size is rounded to the nearest micron.

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Die Bond Pad Coordinate Locations (E -Step)

(Referenced to die center, coordinates in µm) NC = No Connection

SIGNAL NAME	PAD# NUMBER	X/Y CORRDINATES X	Y	PAD SIZE X		Y
INPUT 1	1	-339	572	86	x	86
INPUT 2	2	-263	394	86	x	86
V-	3	-339	-572	86	x	86
STROBE 2	4	-136	-572	86	x	86
OUTPUT 2	5	113	-572	86	x	86
GND	6	372	-572	86	x	86
OUTPUT1	7	372	-122	86	x	86
STROBE 1	8	296	318	86	x	86
VCC	9	194	572	86	x	86
V+	10	17	572	86	x	86

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National Semiconductor

IN U.S.A.
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Fax: 1 207 541 6140

IN EUROPE
Tel: 49 (0) 8141 351492 / 1495
Fax: 49 (0) 8141 351470

IN ASIA PACIFIC
Tel: (852) 27371701

IN JAPAN
Tel: 81 043 299 2308

National Semiconductor Corporation 2900 Semiconductor Drive, P.O. Box 58090, Santa Clara, California 95052-8090

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